Abstracts

A flip chip bonding technology using gold pillars for millimeter-wave applications

S. Aoki, H. Someta, S. Yokokawa, K. Ono, T. Hirose and Y. Ohashi. "A flip chip bonding technology using gold pillars for millimeter-wave applications." 1997 MTT-S International Microwave Symposium Digest 2. (1997 Vol. II [MWSYM]): 731-734.

This paper reports a flip chip bonding technology for a millimeter-wave monolithic integrated circuit (MIMIC) using gold micropillars with a controlled air gap instead of conventional wire bonding. We focus on their electrical performance in the W-band and their reliability against stresses expected in automotive radar applications.

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